

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10812354
<b>Filing Date:</b>	30-Mar-2004
<b>Title of Invention:</b>	Method of improving the wafer to wafer uniformity and defectivity of a deposited dielectric film
<b>First Named Inventor/Applicant Name:</b>	Noriaki Fukiage
<b>Filer:</b>	James Klekotka
<b>Attorney Docket Number:</b>	071469-0308969 (FKL-020)

Filed as Large Entity

### **Utility under 35 USC 111(a) Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>